

Title (en)

SECURE DOCUMENT OR SUPPORT ASSEMBLY

Title (de)

SICHERE DOKUMENT- ODER STÜTZANORDNUNG

Title (fr)

ASSEMBLAGE SECURISÉ DE DOCUMENT OU DE SUPPORT

Publication

**EP 3552154 A1 20191016 (FR)**

Application

**EP 17821834 A 20171207**

Priority

- EP 16306653 A 20161209
- EP 2017081907 W 20171207

Abstract (en)

[origin: WO2018104482A1] The invention relates to a method for producing a security document (1), wherein a body (8, 11) is created that comprises two superimposed layers (12, 15), a circuit (13) which is electric and/or has an electronic chip (3) arranged on the interface between said two layers, and a first adhesive (4) between the two layers, which adheres to the two layers and/or the circuit. The method is characterised in that it comprises a step of depositing a second adhesive (5) which is different from, or has a different behaviour from the first adhesive in relation to the solvents or the temperature and partially adheres to at least one of the two layers (12, 15) and/or the circuit (13).

IPC 8 full level

**G06K 19/077** (2006.01); **G06K 19/073** (2006.01)

CPC (source: EP US)

**C09J 9/00** (2013.01 - US); **G06K 19/07381** (2013.01 - EP US); **G06K 19/0739** (2013.01 - EP US); **G06K 19/07722** (2013.01 - EP US); **G06K 19/07749** (2013.01 - EP US); **G06K 19/0776** (2013.01 - US); **G06K 19/07798** (2013.01 - EP US); **H01L 23/4985** (2013.01 - US); **H01L 23/49855** (2013.01 - US); **H01L 23/573** (2013.01 - US); **H01L 23/66** (2013.01 - US); **H01L 24/29** (2013.01 - US); **H01L 24/83** (2013.01 - US); **H01L 2223/6677** (2013.01 - US); **H01L 2224/29082** (2013.01 - US); **H01L 2224/8385** (2013.01 - US)

Citation (search report)

See references of WO 2018104482A1

Designated contracting state (EPC)

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Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

**EP 3333778 A1 20180613**; EP 3552154 A1 20191016; US 2019311997 A1 20191010; WO 2018104482 A1 20180614

DOCDB simple family (application)

**EP 16306653 A 20161209**; EP 17821834 A 20171207; EP 2017081907 W 20171207; US 201716466825 A 20171207